# TinyLogic UHS Dual 2-Input AND Gate

## Description

The NC7WZ08 is a dual 2–Input AND Gate from ON Semiconductor's Ultra High Speed Series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad  $V_{CC}$  operating range. The device is specified to operate over the 1.65 V to 5.5 V  $V_{CC}$  range. The inputs and output are high impedance when  $V_{CC}$  is 0 V. Inputs tolerate voltages up to 6.5 V independent of  $V_{CC}$  operating voltage.

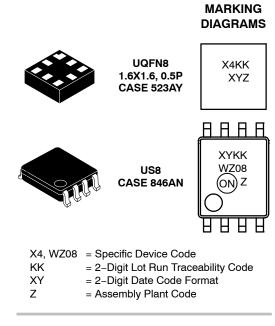
## Features

- Space Saving US8 Surface Mount Package
- MicroPak<sup>TM</sup> Leadless Package
- Ultra High Speed: tPD 2.5 ns Typ. into 50 pF at 5 V V<sub>CC</sub>
- High Output Drive: ±24 mA at 3 V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V  $V_{CC}$
- Power Down High Impedance Inputs / Output
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Patented Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



# **ON Semiconductor®**

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## ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

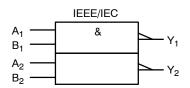


Figure 1. Logic Symbol

# **Connection Diagram**

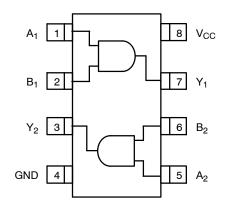
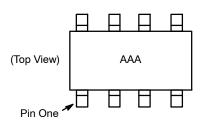


Figure 2. Connection Diagram (Top View)



AAA represents Product Code Top Mark - see ordering code

NOTE: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

#### Figure 3. Pin One Orientation Diagram

# **PIN DESCRIPTION**

Pin Names	Description
A <sub>n</sub> , B <sub>n</sub>	Inputs
Y <sub>n</sub>	Output

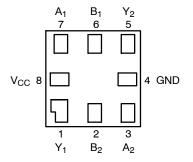


Figure 4. Pad Assignments for MicroPak (Top Thru View)

Inp	Output	
A	В	Y
L	L	L
L	Н	L
н	L	L
Н	Н	Н

H = HIGH Logic Level L = LOW Logic Level

## **ABSOLUTE MAXIMUM RATINGS**

Symbol	Param	eter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	-0.5	6.5	V	
V <sub>IN</sub>	DC Input Voltage		-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.5	V
Ι <sub>ΙΚ</sub>	DC Input Diode Current	V <sub>IN</sub> < -0.5 V	-	-50	mA
Ι <sub>ΟΚ</sub>	DC Output Diode Current	V <sub>OUT</sub> < -0.5 V	-	-50	mA
I <sub>OUT</sub>	DC Output Current	-	±50	mA	
$I_{CC} / I_{GND}$	DC V <sub>CC</sub> / GND Current	-	±100	mA	
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
TJ	Junction Temperature Under Bias	Junction Temperature Under Bias			°C
ΤL	Junction Lead Temperature (Sold	-	260	°C	
PD	Power Dissipation @ +85°C US8		-	245	mW
		MicroPak-8	-	165	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## **RECOMMENDED OPERATING CONDITIONS**

Symbol		Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC}$ = 1.8 V ±0.15 V, 2.5 V ±0.2 V		0	20	ns/V
		V <sub>CC</sub> = 3.3 V ±0.3 V	0	10	
	$V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$		0	5	1
$\theta_{JA}$	Thermal Resistance US8		-	265	°C/W
		MicroPak-8	-	395	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability. 1. Unused inputs must be held HIGH or LOW. They may not float.

# DC ELECTICAL CHARACTERISTICS

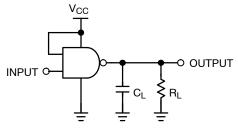
					T <sub>A</sub> = +25°C			T <sub>A</sub> = −40 to +85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	Co	onditions	Min	Тур	Max	Min	Max	Unit
VIH HIGH Level Input		1.65 – 1.95			0.65 V <sub>CC</sub>	-	-	0.65 V <sub>CC</sub>	-	V
	Voltage	2.3 – 5.5			0.7 V <sub>CC</sub>	-	-	0.7 V <sub>CC</sub>	-	
V <sub>IL</sub>	LOW Level Input	1.65 – 1.95			-	-	0.35 V <sub>CC</sub>	-	0.35 V <sub>CC</sub>	V
	Voltage	2.3 – 5.5			-	-	0.3 V <sub>CC</sub>	-	0.3 V <sub>CC</sub>	
V <sub>OH</sub>	HIGH Level Output	1.65	$V_{IN} = V_{IH}$	I <sub>OH</sub> = -100 μA	1.55	1.65	-	1.55	-	V
	Voltage	2.3			2.2	2.3	-	2.2	-	
		3.0			2.9	3.0	-	2.9	-	
		4.5			4.4	4.5	-	4.4	-	
		1.65		I <sub>OH</sub> = -4 mA	1.29	1.52	-	1.29	-	
		2.3		I <sub>OH</sub> = -8 mA	1.9	2.15	-	1.9	-	
		3.0		I <sub>OH</sub> = -16 mA	2.5	2.80	-	2.4	-	
		3.0		I <sub>OH</sub> = -24 mA	2.4	2.68	-	2.3	-	
		4.5		I <sub>OH</sub> = -32 mA	3.9	4.20	-	3.8	-	
V <sub>OL</sub>	LOW Level Output	1.65	$V_{IN} = V_{IL}$	I <sub>OL</sub> = 100 μA	-	0.0	0.1	-	0.1	V
	Voltage	2.3			-	0.0	0.1	-	0.1	
		3.0			-	0.0	0.1	-	0.1	
		4.5			-	0.0	0.1	-	0.1	
		1.65		I <sub>OL</sub> = 4 mA	-	0.08	0.24	-	0.24	-
		2.3		I <sub>OL</sub> = 8 mA	_	0.10	0.3	_	0.3	-
		3.0		I <sub>OL</sub> = 16 mA	-	0.15	0.4	-	0.4	-
		3.0		I <sub>OL</sub> = 24 mA	-	0.22	0.55	-	0.55	-
		4.5		I <sub>OL</sub> = 32 mA	-	0.22	0.55	-	0.55	-
I <sub>IN</sub>	Input Leakage Current	1.65 – 5.5	V <sub>IN</sub> = 5.5 V	V, GND	-	-	±0.1	_	±1	μA
I <sub>OFF</sub>	Power Off Leakage Current	0.0	$V_{\rm IN}$ or $V_{\rm OUT}$ = 5.5 V		-	-	1	-	10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	1.65 – 5.5	V <sub>IN</sub> = 5.5 V	/, GND	-	-	1	_	10	μA

# AC ELECTRICAL CHARACTERISTICS

				$T_A = +25^{\circ}C$ $T_A = -40$ to			to +85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	1.8 ±0.15	$C_{L} = 15 \text{ pF},$	-	5.7	10.5	-	11.0	ns
	(Figure 5, 7)	2.5 ±0.2	· R <sub>L</sub> = 1 MΩ,	-	3.5	5.8	-	6.2	
		3.3 ±0.3		-	2.6	3.9	-	4.3	
		5.0 ±0.5		-	1.9	3.1	-	3.3	
		3.3 ±0.3	C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω,	-	3.2	4.8	-	5.2	
		5.0 ±0.5	n_ = 500 s2,	-	2.5	3.7	-	4.0	
C <sub>IN</sub>	Input Capacitance	0		-	2.5	-	-	-	pF
C <sub>PD</sub>	Power Dissipation Capacitance	3.3	(Note 2)	-	14.5	-	-	-	pF
	(Figure 6)	5.0		-	19.5	-	-	-	

2.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. (see Figure 6)  $C_{PD}$  is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = ( $C_{PD}$ ) (V<sub>CC</sub>) (f<sub>IN</sub>) + (I<sub>CC</sub>static).

#### AC Loading and Waveforms

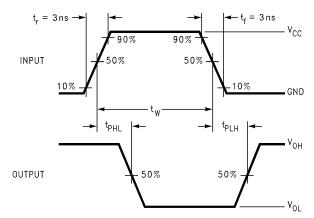


 $C_L$  includes load and stray capacitance Input PRR = 1.0 MHz,  $t_W$  = 500 ns

# Figure 5. AC Test Circuit

Input = AC Waveform;  $t_r = t_f = 1.8$  ns; PRR = 10 MHz; Duty Cycle = 50%.

## Figure 6. I<sub>CCD</sub> Test Circuit



## Figure 7. AC Waveforms

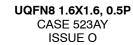
#### **ORDERING INFORMATION**

Order Number	Top Mark	Package	Shipping <sup>†</sup>
NC7WZ08K8X	WZ08	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ08L8X	X4	8-Lead MicroPak, 1.6 mm Wide	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
3. All packages are lead free per JEDEC: J-STD-020B standard.

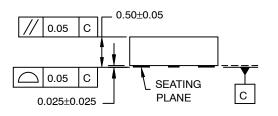
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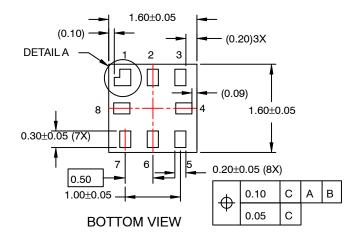


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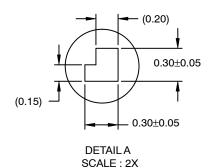
SIDE VIEW





NOTES:

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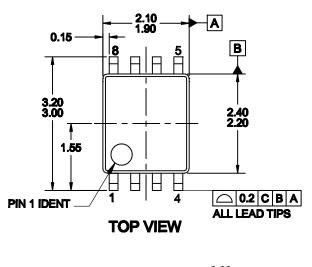
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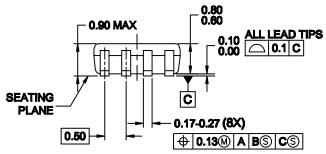
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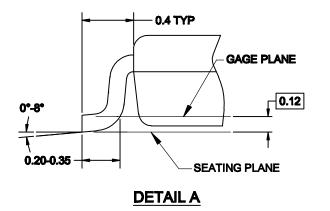
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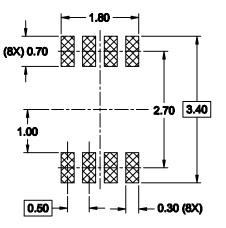
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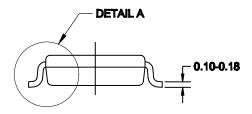




# **RECOMMENDED LAND PATTERN**

# NOTES:

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